

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5464	(lead near frame or leadframe) and lead near2 (feet or distal or tie or end or digits or outer or outside) and (wirebond or wire near bond or wire near bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 09:06
L2	2405	(lead near frame or leadframe) same lead near2 (feet or distal or tie or end or digits or outer or outside) same (wirebond or wire near bond or wire near bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 09:07
L3	179	(lead near frame or leadframe) same lead near2 (feet or distal or tie or end or digits or outer or outside) near4 (bent or bending or fold or folded or folding or curved or curving or angled or angle or angling or under or underneath or below or beneath) same (wirebond or wire near bond or wire near bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 12:11
L4	910	(lead-on-chip or lead adj chip) and (lead) near4 (gull or j or bent or bending or curved or folded or curve or acute)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 12:12
L5	603	(lead-on-chip or lead adj chip) and (lead) near4 (gull or j or bent or bending or curved or folded or curve or acute) and (wirebond or wire near bond or wire near bonding or wirebonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 12:13
L7	315	(lead-on-chip or lead adj chip) and (lead) near4 (foot or end or distal or outer or outside) near5 (gull or j or wing or bent or bending or folded or acute) and (wirebond or wire near bond or wire near bonding or wirebonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 13:41
L14	669	(lead near frame or leadframe) and gull near wing and (wirebond or wirebonding or wire near bond or wire near bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 14:02
L15	180	(lead near frame or leadframe) and gull near wing and (wirebond or wirebonding or wire near bond or wire near bonding) and (loc or lead adj chip or lead-on-chip or lead-over-chip or (lead or diepad) near3 (over or above or below or beneath or under or lower or underneath or top) near3 (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 14:11
L17	6	(US-20010017410-\$).did. or (US-6097081-\$ or US-6319753-\$ or US-6175149-\$).did. or (JP-06125021-\$ or JP-62117355-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2005/04/27 14:22
S1	83	(lead near frame or leadframe) near8 (profile or height) near2 (reduced or reducing or minimized or low or short or small or minimal or minimum or decreased or decreasing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 09:04
S2	132	(package or leadframe or lead adj frame or housing) same (lead near foot or gull near wing or j near lead) same (profile or height)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 16:02
S3	5635	(package or leadframe or lead adj frame or housing) same (lead) near4 (bent or angle or angled)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 16:03

S4	162	(package or leadframe or lead adj frame or housing) same (lead) near4 (bent or angle or angled) near6 (recess or recessed or under or underneath or below or beneath or folded or lower or folding) near5 (package or housing or base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 16:42
S5	54	(package or leadframe or lead adj frame or housing) same (lead) near4 (acute)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 17:01
S6	2	(package or leadframe or lead adj frame or housing) same reverse near gull	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 17:01